TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260223001.1
AMC0311S and AMC0311D Design Change
Change Notification / Sample Request

Date: February 23, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260223001.1
Attachment

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
AMC0311DDWVR	NULL
AMC0311SDWVR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260223001.1	**PCN Date:**	February 23, 2026
Title:	AMC0311S and AMC0311D Design Change		
Customer Contact:	Change Management Team	**Dept:**	Quality Services
Proposed 1st Ship Date:	May 24, 2026	**Sample requests accepted until:**	April 24, 2026*

***Sample requests received after April 24, 2026 will not be supported.**

Change Type:

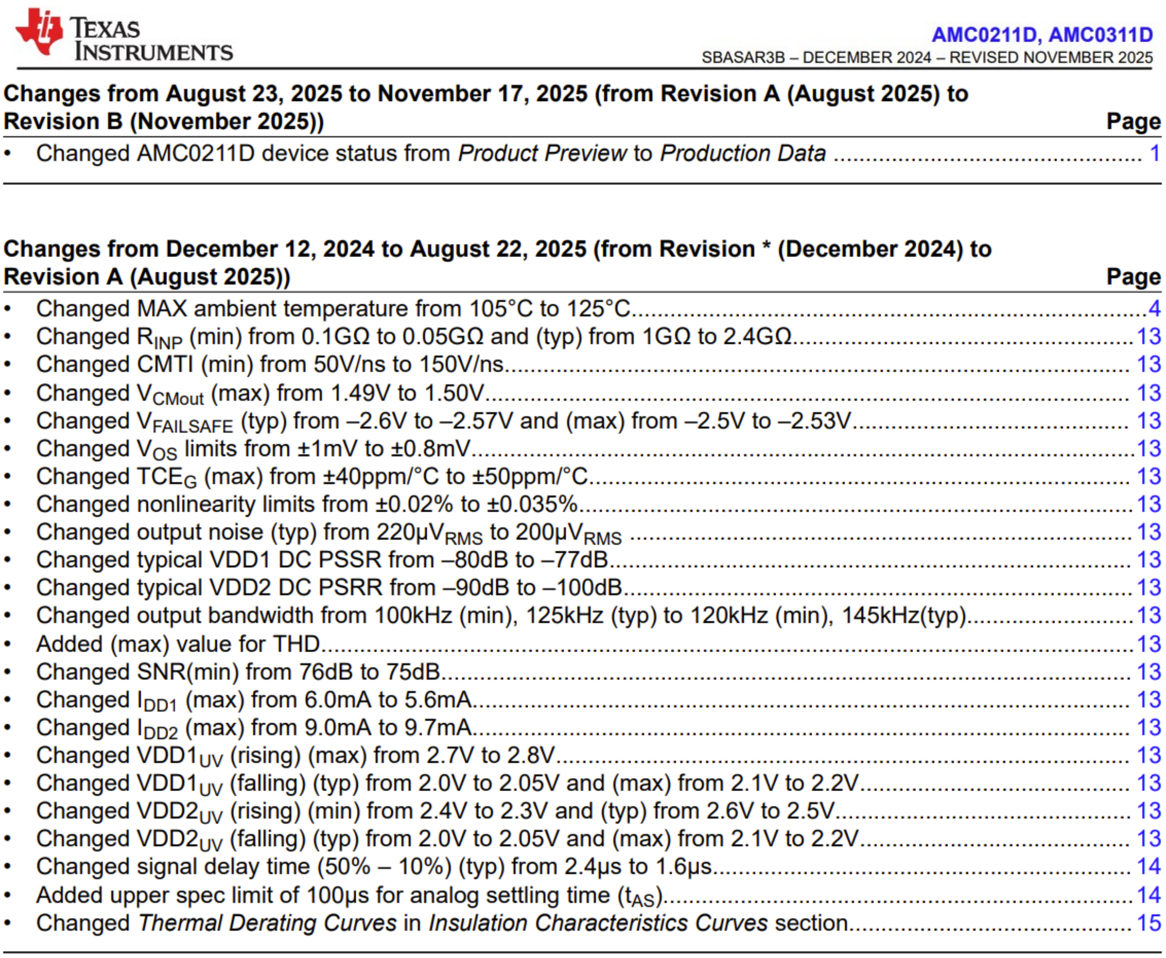
☐	Assembly Site	☒	Design	☐	Wafer Bump Material
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Process
☐	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

This notification is to inform of a AMC0311S and AMC0311D Design Change resulting in LU, CMTI and SNR improvements.

The product datasheet(s) is updated as seen in the change revision history below:



AMC0211D, AMC0311D
SBASAR3B – DECEMBER 2024 – REVISED NOVEMBER 2025

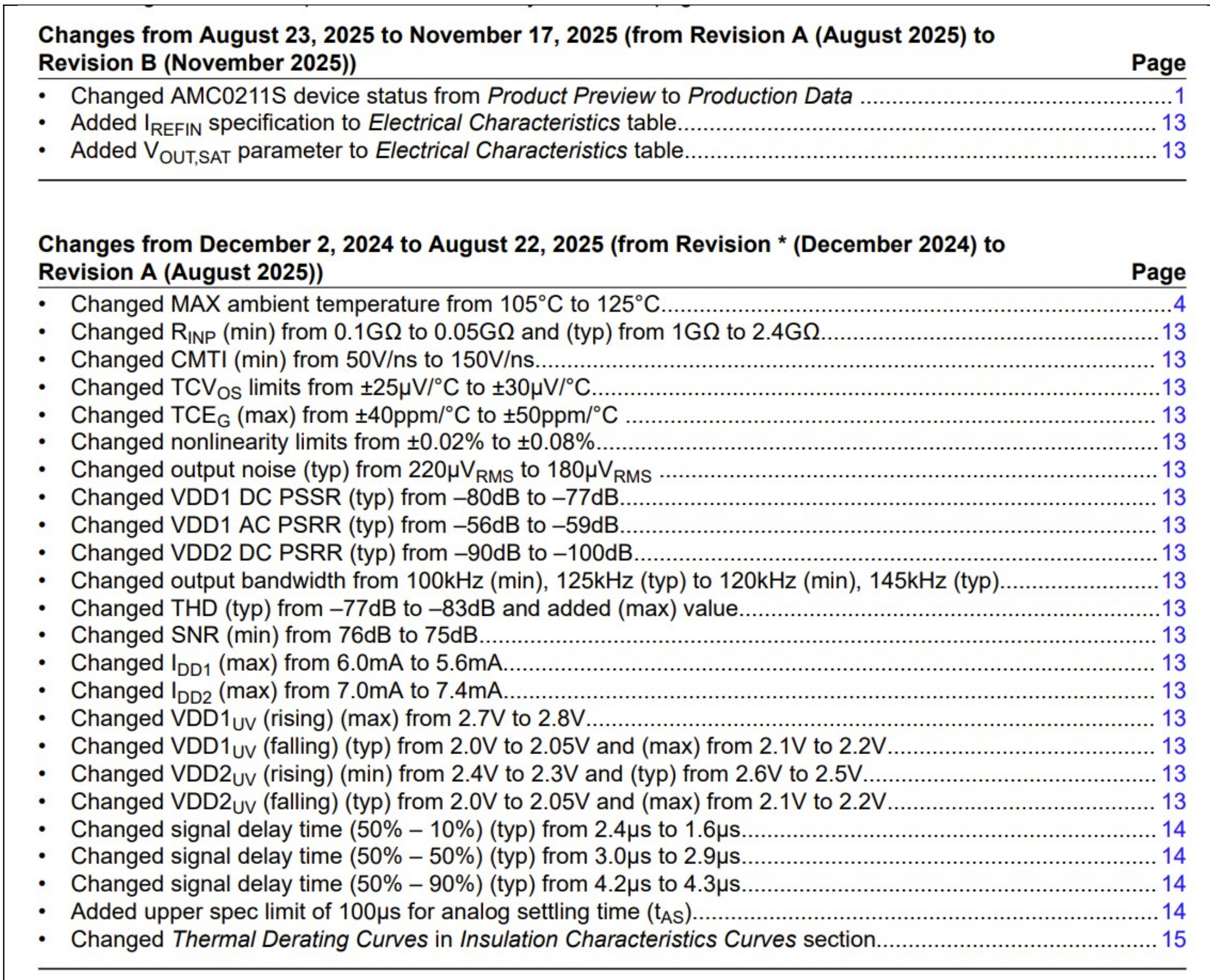
Changes from August 23, 2025 to November 17, 2025 (from Revision A (August 2025) to Revision B (November 2025)) **Page**

- Changed AMC0211D device status from *Product Preview* to *Production Data* 1

Changes from December 12, 2024 to August 22, 2025 (from Revision * (December 2024) to Revision A (August 2025)) **Page**

- Changed MAX ambient temperature from 105°C to 125°C..... 4
- Changed R_{INP} (min) from 0.1GΩ to 0.05GΩ and (typ) from 1GΩ to 2.4GΩ..... 13
- Changed CMTI (min) from 50V/ns to 150V/ns..... 13
- Changed V_{CMout} (max) from 1.49V to 1.50V..... 13
- Changed $V_{FAILSAFE}$ (typ) from –2.6V to –2.57V and (max) from –2.5V to –2.53V..... 13
- Changed V_{OS} limits from ±1mV to ±0.8mV..... 13
- Changed TCE_G (max) from ±40ppm/°C to ±50ppm/°C..... 13
- Changed nonlinearity limits from ±0.02% to ±0.035%..... 13
- Changed output noise (typ) from 220μV_{RMS} to 200μV_{RMS} 13
- Changed typical VDD1 DC PSSR from –80dB to –77dB..... 13
- Changed typical VDD2 DC PSRR from –90dB to –100dB..... 13
- Changed output bandwidth from 100kHz (min), 125kHz (typ) to 120kHz (min), 145kHz(typ)..... 13
- Added (max) value for THD..... 13
- Changed SNR(min) from 76dB to 75dB..... 13
- Changed I_{DD1} (max) from 6.0mA to 5.6mA..... 13
- Changed I_{DD2} (max) from 9.0mA to 9.7mA..... 13
- Changed $VDD1_{UV}$ (rising) (max) from 2.7V to 2.8V..... 13
- Changed $VDD1_{UV}$ (falling) (typ) from 2.0V to 2.05V and (max) from 2.1V to 2.2V..... 13
- Changed $VDD2_{UV}$ (rising) (min) from 2.4V to 2.3V and (typ) from 2.6V to 2.5V..... 13
- Changed $VDD2_{UV}$ (falling) (typ) from 2.0V to 2.05V and (max) from 2.1V to 2.2V..... 13
- Changed signal delay time (50% – 10%) (typ) from 2.4μs to 1.6μs..... 14
- Added upper spec limit of 100μs for analog settling time (t_{AS})..... 14
- Changed *Thermal Derating Curves* in *Insulation Characteristics Curves* section..... 15

AMC0211S, AMC0311S
SBASB13B – DECEMBER 2024 – REVISED NOVEMBER 2025



Changes from August 23, 2025 to November 17, 2025 (from Revision A (August 2025) to Revision B (November 2025)) **Page**

- Changed AMC0211S device status from *Product Preview* to *Production Data* 1
- Added I_{REFIN} specification to *Electrical Characteristics* table.......... 13
- Added $V_{OUT,SAT}$ parameter to *Electrical Characteristics* table.......... 13

Changes from December 2, 2024 to August 22, 2025 (from Revision * (December 2024) to Revision A (August 2025)) **Page**

- Changed MAX ambient temperature from 105°C to 125°C.......... 4
- Changed R_{INP} (min) from 0.1GΩ to 0.05GΩ and (typ) from 1GΩ to 2.4GΩ.......... 13
- Changed CMTI (min) from 50V/ns to 150V/ns.......... 13
- Changed TCV_{OS} limits from ±25µV/°C to ±30µV/°C.......... 13
- Changed TCE_G (max) from ±40ppm/°C to ±50ppm/°C 13
- Changed nonlinearity limits from ±0.02% to ±0.08%.......... 13
- Changed output noise (typ) from 220µV_{RMS} to 180µV_{RMS} 13
- Changed VDD1 DC PSSR (typ) from –80dB to –77dB.......... 13
- Changed VDD1 AC PSRR (typ) from –56dB to –59dB.......... 13
- Changed VDD2 DC PSRR (typ) from –90dB to –100dB.......... 13
- Changed output bandwidth from 100kHz (min), 125kHz (typ) to 120kHz (min), 145kHz (typ).......... 13
- Changed THD (typ) from –77dB to –83dB and added (max) value.......... 13
- Changed SNR (min) from 76dB to 75dB.......... 13
- Changed I_{DD1} (max) from 6.0mA to 5.6mA.......... 13
- Changed I_{DD2} (max) from 7.0mA to 7.4mA.......... 13
- Changed $VDD1_{UV}$ (rising) (max) from 2.7V to 2.8V.......... 13
- Changed $VDD1_{UV}$ (falling) (typ) from 2.0V to 2.05V and (max) from 2.1V to 2.2V.......... 13
- Changed $VDD2_{UV}$ (rising) (min) from 2.4V to 2.3V and (typ) from 2.6V to 2.5V.......... 13
- Changed $VDD2_{UV}$ (falling) (typ) from 2.0V to 2.05V and (max) from 2.1V to 2.2V.......... 13
- Changed signal delay time (50% – 10%) (typ) from 2.4µs to 1.6µs.......... 14
- Changed signal delay time (50% – 50%) (typ) from 3.0µs to 2.9µs.......... 14
- Changed signal delay time (50% – 90%) (typ) from 4.2µs to 4.3µs.......... 14
- Added upper spec limit of 100µs for analog settling time (t_{AS}).......... 14
- Changed *Thermal Derating Curves* in *Insulation Characteristics Curves* section.......... 15

Product Folder	Current Datasheet Number	New Datasheet Number	Link to Full Datasheet
AMC0x11D	SBASAR3	SBASAR3B	http://www.ti.com/product/AMC0211D
AMC0x11S	SBASB13	SBASB13B	http://www.ti.com/product/AMC0211S

** The design changes are specific to RevA of the data sheets. The datasheet rev B is the latest released datasheet available for review on ti.com.

Qual details are provided in the Qual Data Section.

Reason for Change:

Improve device performance.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None. Review standard data package (SDP)

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

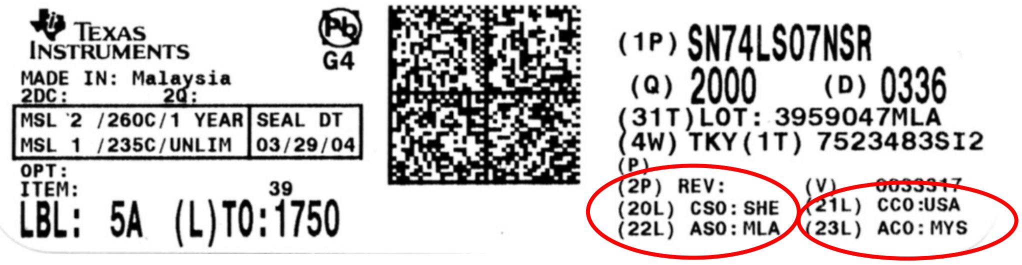
RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Die Rev:

Current Die Rev [2P]	**New** **Die Rev [2P]**
B	**C**

Sample product shipping label (not actual product label):



TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected

AMC0311DDWVR	AMC0311SDWVR

Product Attributes

Attributes	Qual Device: AMC0311DQDWVRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LP87332ARHDRQ1	QBS Process Reference: AMC23C12QDWVRQ1	QBS Package, Process, Product Reference: AMC0306M05QDWVRQ1
Automotive Grade Level	Grade 1	Grade 1	Grade 1	Grade 1	Grade 1
Operating Temp Range (C)	-40 to 125	-40 to 125	-40 to 125	-40 to 125	-40 to 125
Product Function	Signal Chain	Signal Chain	Power Management	Signal Chain	Signal Chain
Wafer Fab Supplier	RFAB, MH8	MH8, DMOS6	RFAB	MH8, DMOS6	RFAB, MH8
Assembly Site	MLA	MLA	UTL1	TAI	MLA
Package Group	SOIC	SOIC	QFN	SOIC	SOIC
Package Designator	DWV	D	RHD	DWV	DWV
Pin Count	8	8	28	8	8

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device AMC0311DQDWVRQ1 is qualified at MSL2 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AMC0311DQDWVRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LP87332ARHDRQ1	QBS Process Reference: AMC23C12QDWVRQ1	QBS Package, Process, Product Reference: AMC0306M05QDWVRQ1
Test Group A - Accelerated Environment Stress Tests												
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL2 260C	-	-	-	-	-	3/0/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AMC0311DQDWVRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LP87332ARHDRQ1	QBS Process Reference: AMC23C12QDWVRQ1	QBS Package, Process, Product Reference: AMC0306M05QDWVRQ1
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	-	-	-	-	1/5/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0
Test Group B - Accelerated Lifetime Simulation Tests												
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	1000 Hours	-	-	3/231/0	-	-
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	408 Hours	-	-	-	3/231/0	1/77/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	3/2400/0	-
Test Group C - Package Assembly Integrity Tests												
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	-	-	-
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	-	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	1/15/0	-	-	-
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0	-	-	-
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	-	-	-	-
Test Group D - Die Fabrication Reliability Tests												
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: AMC0311DQDWVRQ1	QBS Package Reference: AMC22C12QDRQ1	QBS Process Reference: LP87332ARHDRQ1	QBS Process Reference: AMC23C12QDWVRQ1	QBS Package, Process, Product Reference: AMC0306M05QDWVRQ1
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests												
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0	-	-	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0	-	-	-	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	1/3/0	-	-	-	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0	-	-	-	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Orderable Part Numbers

The following table contains a list of all TI Orderable Part Numbers (OPNs) released by this qualification per Product Qualification Family definition (AEC Q100 Appendix 1). Group E results shown above cover all part numbers listed here.

AMC0311DQDWVRQ1	AMC0311RQDWVRQ1
AMC0311SQDWVRQ1	AMC0330DQDWVRQ1
AMC0330RQDWVRQ1	AMC0330SQDWVRQ1

Ambient Operating Temperature by Automotive Grade Level:

- Grade 0 (or E): -40C to +150C
- Grade 1 (or Q): -40C to +125C
- Grade 2 (or T): -40C to +105C
- Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

- Room/Hot/Cold : HTOL, ED
- Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
- Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-NPD-2402-149

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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